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TO:	**EXAMINER**	**Tuan T. Dinh**
	ART UNIT	**2827**
	EXAMINER'S FAX NUMBER	**(703) 872-9318**

FROM: Peter S. Zawilski

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RE:	**SERIAL NO.**	**10/001,271**
	DOCKET NO.	**US 018154**

3 Pages (including cover sheet)

This transmission includes:

Response to Restriction Requirement 14-JAN-2003

Certificate of Transmission under 37 CFR 1.8

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on February 3, 2003.

Peter Zawilski

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:
Mike C. Loo.
Serial No. 10/001,271
Filed: December 4, 2001
For: Optimum Power and Ground Bump Pad and Bump Patterns for Flip Chip Packaging

Group: 2827
Examiner: Tuan T. Dinh
Docket No.: **US 018154**

AMENDMENT UNDER 37 CFR §1.111

Assistant Commissioner of Patents
Washington, DC 20231

Sir:

In response to the Official Action dated January 14, 2003, please amend this application as set forth below. Please change docket number as noted above.

Please amend the application as follows:

In the Claims

Please cancel claim 11 through 17 without prejudice.

Remarks

Applicant acknowledges Examiner's imposing of restriction on submitted claims per 35 U.S.C. §121.

Applicant elects to prosecute claims 1 through 10, drawn to a method for fabricating a semiconductor structure, classified in **class 177, subclass 262.**

Applicant respectfully traverses Examiner's requirement for election of patentable distinct species of the claimed invention. Figure 2 explains "for optimum routing and electrical performance it is necessary to position the chip bumps for power and ground bumps at specific positions. Without this, optimum results are not obtained. . .Some of the signals need to go to the second layer and back through the first layer through microvias. Routing will be more difficult. . .(page 3, paragraph 0013 of Specification)" Figure 2 is outlining the challenge involved if the present invention is not used. Figure 3 outlines an example embodiment of the claimed invention. "Ideally, it is desirable that connections from a bump pad to a plane be made in as direct a manner as possible. Figure 3 illustrates one such arrangement. . .(page 3, paragraph 0014 of Specification)".

Therefore, there is no Species I as asserted by the Examiner. Claims 1 – 5 would likely map to Species II.

Figures 4(a) and 4(b) illustrates the arrangement of chip bumps in either in an orthogonal pattern, as in Figure 4(a) or in a staggered pattern, as in Figure 4(b). Again, Applicant believes no distinct Species III and IV have been claimed. Claims 6 – 10 may be applicable to both.

Applicant is puzzled at Examiner's imposition of two restriction requirements. Applicant clearly sees the rationale for the restriction as stated in Paragraphs 1 through 4.. of the Office Action. Paragraph 5 in imposing restrictions as to patentably distinct features is readily applicable to chemistry-related inventions and Markush practice. However, Applicant fails to see its applicability in his claimed invention related to "Flip Chip" packaging. Applicant respectfully requests that the restriction requirement imposed in paragraph 5 of the Office Action be removed.

If Applicant conditionally elects claims 1 –5 directed to Species II within the election of claims 1 – 10 mentioned *infra*.

Please charge any fees other than the issue fee and credit any overpayments to Deposit Account 14-1270.

Respectfully submitted,

By _____
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